

Liangbiao Chen

List of Publications by Year in descending order

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Version: 2024-02-01

19
papers

173
citations

1040056

9
h-index

1125743

13
g-index

19
all docs

19
docs citations

19
times ranked

254
citing authors

| # | ARTICLE | IF | CITATIONS |
|----|---|------|-----------|
| 1 | Design and adjustment of the graphene work function via size, modification, defects, and doping: a first-principle theory study. <i>Nanoscale Research Letters</i> , 2017, 12, 642. | 5.7 | 28 |
| 2 | A convection–diffusion porous media model for moisture transport in polymer composites: Model development and validation. <i>Journal of Polymer Science, Part B: Polymer Physics</i> , 2015, 53, 1440-1449. | 2.1 | 18 |
| 3 | Modeling nonlinear moisture diffusion in inhomogeneous media. <i>Microelectronics Reliability</i> , 2017, 75, 162-170. | 1.7 | 18 |
| 4 | A First-Principle Theoretical Study of Mechanical and Electronic Properties in Graphene Single-Walled Carbon Nanotube Junctions. <i>Materials</i> , 2017, 10, 1300. | 2.9 | 15 |
| 5 | Investigation of impact dynamics of roof bolting with passive friction control. <i>International Journal of Rock Mechanics and Minings Sciences</i> , 2014, 70, 559-568. | 5.8 | 13 |
| 6 | Modeling of moisture over-saturation and vapor pressure in die-attach film for stacked-die chip scale packages. <i>Journal of Materials Science: Materials in Electronics</i> , 2016, 27, 481-488. | 2.2 | 12 |
| 7 | Effects of Vapor Pressure and Super-Hydrophobic Nanocomposite Coating on Microelectronics Reliability. <i>Engineering</i> , 2015, 1, 384-390. | 6.7 | 10 |
| 8 | A Review on Water Vapor Pressure Model for Moisture Permeable Materials Subjected to Rapid Heating. <i>Applied Mechanics Reviews</i> , 2018, 70, . | 10.1 | 10 |
| 9 | The Effects of Graphene Stacking on the Performance of Methane Sensor: A First-Principles Study on the Adsorption, Band Gap and Doping of Graphene. <i>Sensors</i> , 2018, 18, 422. | 3.8 | 9 |
| 10 | Experimental study on the dynamic mechanical properties of titanium alloy after thermal oxidation. <i>Applied Physics A: Materials Science and Processing</i> , 2016, 122, 1. | 2.3 | 7 |
| 11 | An Arrhenius-type constitutive model to predict the deformation behavior of Sn0.3Ag0.7Cu under different temperature. <i>Journal of Materials Science: Materials in Electronics</i> , 2019, 30, 14611-14620. | 2.2 | 7 |
| 12 | Die and Package Level Thermal and Thermal/Moisture Stresses in 3D Packaging: Modeling and Characterization. <i>Springer Series in Advanced Microelectronics</i> , 2017, , 293-332. | 0.3 | 6 |
| 13 | An Insight to High Humidity-Caused Friction Modulation of Brake by Numerical Modeling of Dynamic Meniscus under Shearing. <i>Lubricants</i> , 2015, 3, 437-446. | 2.9 | 5 |
| 14 | LED's luminous flux lifetime prediction using a hybrid numerical approach. , 2015, , . | | 5 |
| 15 | A Novel Interconnected Structure of Graphene-Carbon Nanotubes for the Application of Methane Adsorption. <i>IEEE Sensors Journal</i> , 2018, 18, 1555-1561. | 4.7 | 5 |
| 16 | A Unified and Versatile Model Study for Moisture Diffusion. , 2017, , . | | 4 |
| 17 | Experimental and numerical study on dynamic mechanical behaviors of low-silver lead-free solder under combined compression-shear loadings. <i>Journal of Materials Science: Materials in Electronics</i> , 2019, 30, 18678-18685. | 2.2 | 1 |
| 18 | Testing and Modeling of Board Level Reliability of WLCSP under UHAST Conditions. , 2021, , . | | 0 |

| # | ARTICLE | IF | CITATIONS |
|----|---|-----|-----------|
| 19 | Die and Package Level Thermal and Thermal/Moisture Stresses in 3-D Packaging: Modeling and Characterization. Springer Series in Advanced Microelectronics, 2021, , 431-469. | 0.3 | 0 |